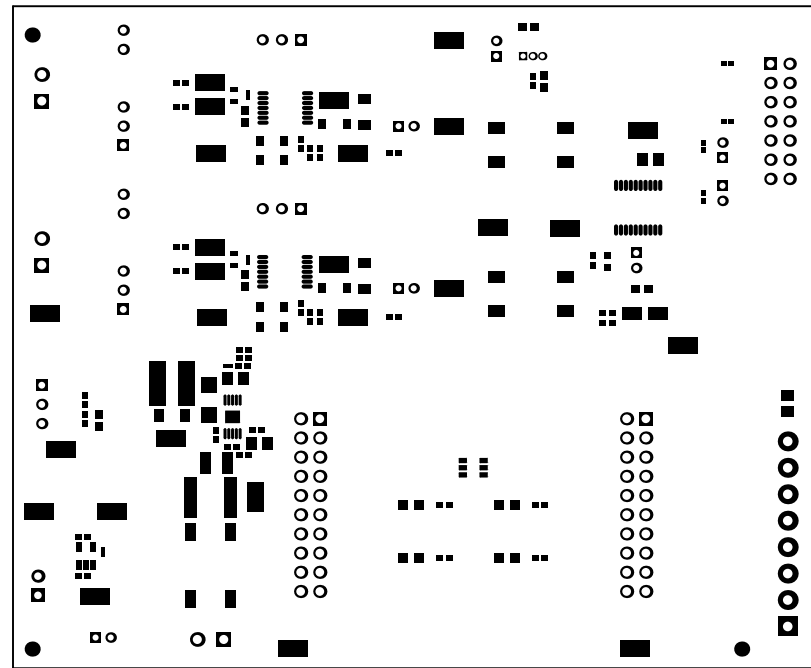
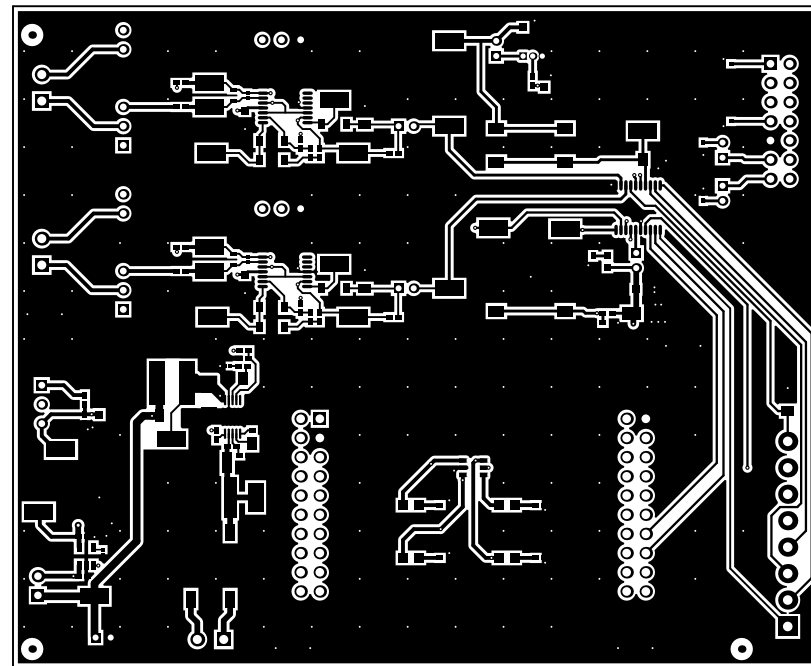


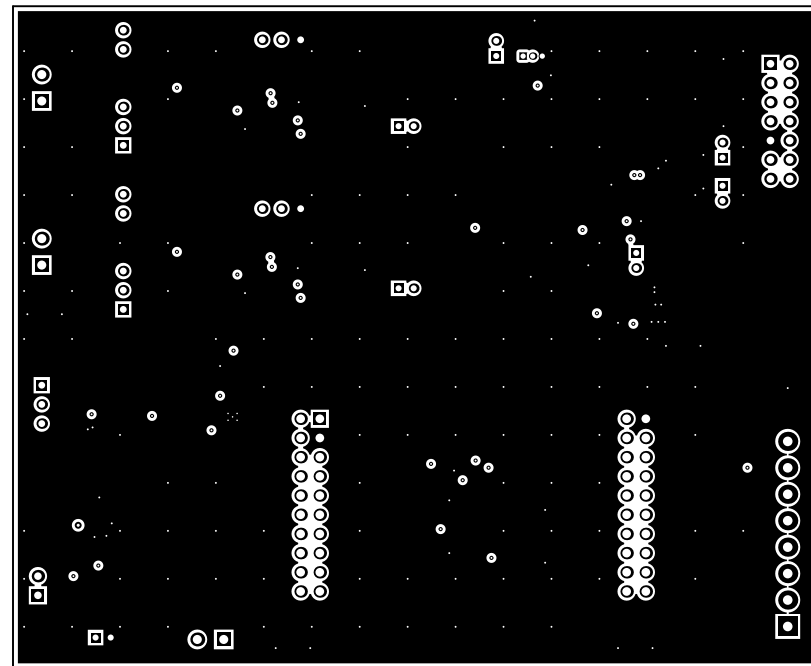
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01070		
PLOT NAME = Top Overlay	GENERATED : 9/2/2016 10:13:21 AM	TEXAS INSTRUMENTS	



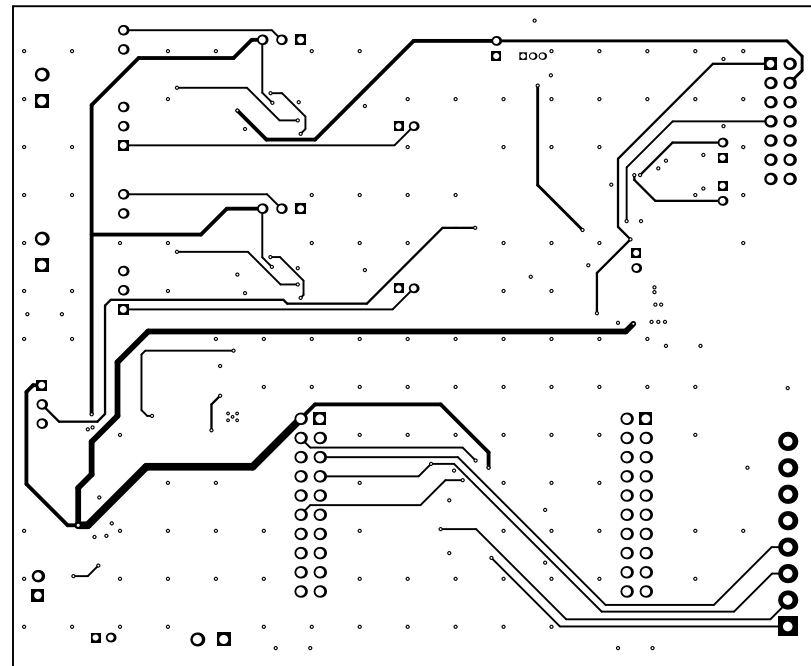
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01070		
PLOT NAME = Top Solder Mask	GENERATED : 9/2/2016 10:13:22 AM	TEXAS INSTRUMENTS	



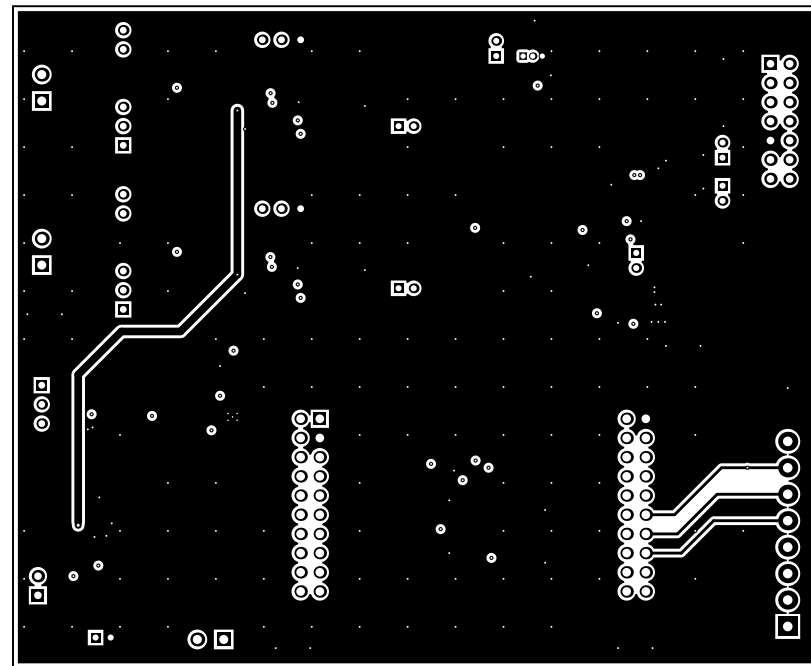
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01070		
PLOT NAME = Top Layer	GENERATED : 9/2/2016 10:13:22 AM	TEXAS INSTRUMENTS	



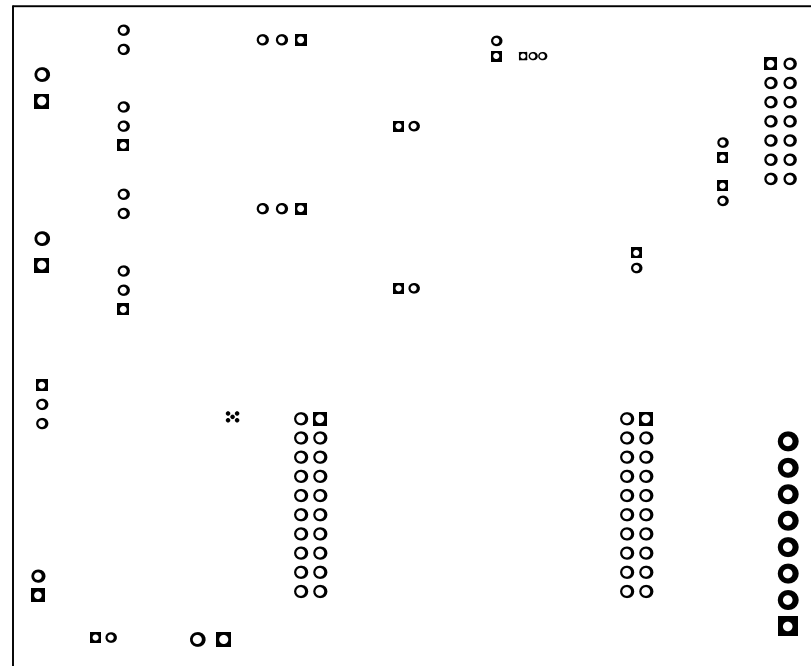
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: TIDA-01070		
PLOT NAME = Signal Layer 1	GENERATED : 9/2/2016 10:13:23 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: TIDA-01070		
PLOT NAME = Signal Layer 2	GENERATED : 9/2/2016 10:13:23 AM	TEXAS INSTRUMENTS	

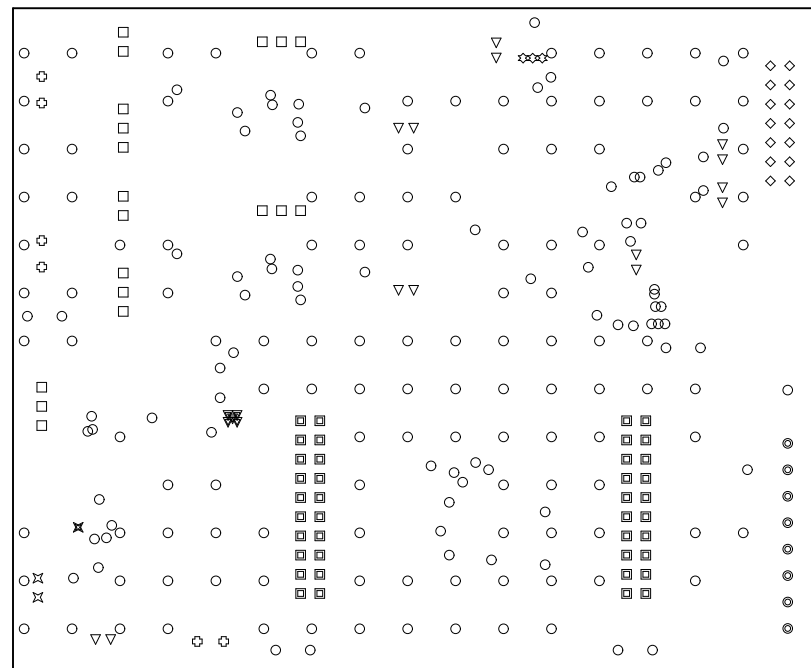


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01070		
PLOT NAME = Bottom Layer	GENERATED : 9/2/2016 10:13:24 AM	TEXAS INSTRUMENTS	

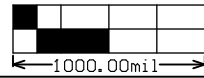
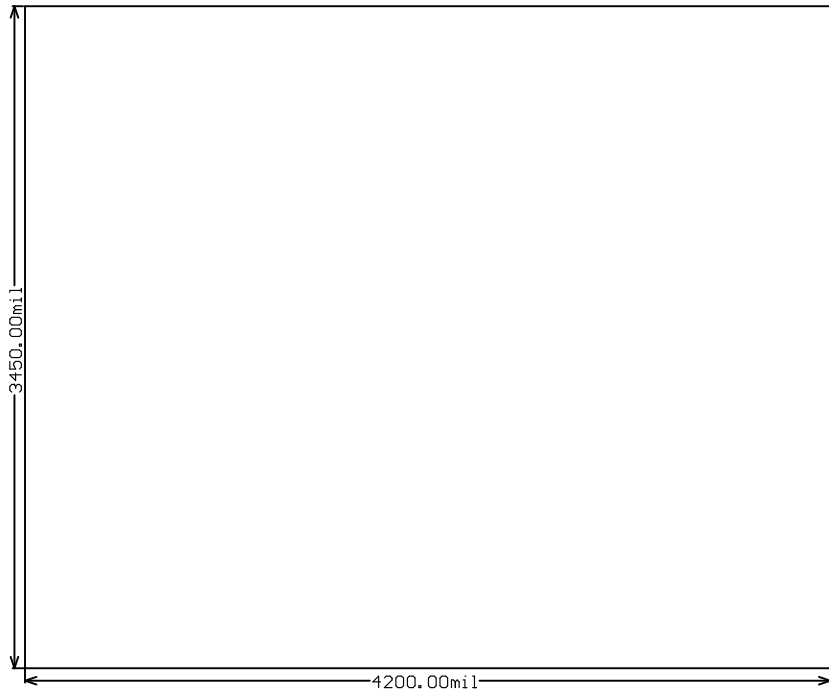


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01070		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/2/2016	10:13:24 AM	TEXAS INSTRUMENTS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
✕	1	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v91h41m0mx0
✕	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
✱	3	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
▽	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h20
⊕	6	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
⊙	8	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
▽	14	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
◇	14	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
□	19	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
■	40	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
○	203	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v56h25m0mx0
	315 Total							



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01070		
PLOT NAME = Drill Drawing	GENERATED : 9/2/2016 10:13:25 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01070	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01070		
PLOT NAME = Board Dimensions	GENERATED : 9/2/2016	10:13:25 AM	TEXAS INSTRUMENTS

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